

Title (en)
METHOD OF FORMING AN IN-SITU RECESSED STRUCTURE

Title (de)
VERFAHREN ZUR BILDUNG EINER IN-SITU VERTIEFTEN STRUKTUR

Title (fr)
PROCEDE DE FORMATION DE STRUCTURE EN RETRAIT IN SITU

Publication
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Application
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- US 94615904 A 20040921
- US 94656504 A 20040921

Abstract (en)
[origin: WO2006033872A2] The present invention features a method of patterning a substrate that includes forming, on the substrate, a multi-layer film with a surface, an etch rate interface and an etch-differential interface. The etch-differential interface is defined between the etch rate interface and the surface. A recorded pattern is transferred onto the substrate defined, in part, by the etch-differential interface. The recorded pattern has etched pattern characteristics (EPC) that define the shape of the pattern formed for a given etch process or set of etch processes. The etch-differential interface modifies the EPC. By establishing a suitable etch-differential interface, one may obtain a recorded pattern that differs substantially in shape compared with the shape of the patterned layer or the same pattern may be obtained.

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Citation (search report)

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- See references of WO 2006033872A2

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